PRELIMINARY PRODUCT INFORMATION



BIPOLAR ANALOG INTEGRATED CIRCUIT µPC8236T6N

SiGe:C LOW NOISE AMPLIFIER FOR GPS

DESCRIPTION

The μ PC8236T6N is a silicon germanium carbon (SiGe:C) monolithic integrated circuit designed as low noise amplifier for GPS. This device exhibits low noise figure and high power gain characteristics, so this IC can improve the sensitivity of GPS receiver. In addition, the μ PC8236T6N which is included output matching circuit contributes to reduce external components and system size.

The package is a 6-pin plastic TSON (Thin Small Out-line Non-leaded) suitable for surface mount.

This IC is manufactured using our UHS4 (<u>Ultra High Speed Process</u>) SiGe:C bipolar process.

FEATURES

Low noise : NF = 0.8 dB TYP. @ fin = 1 575 MHz
 High gain : GP = 19.5dB TYP. @ fin = 1 575 MHz
 Low current consumption : Icc = 6.5 mA TYP. @ Vcc = 2.7 V

Built-in power-saving function

High-density surface mounting : 6-pin plastic TSON package (1.5 x 1.5 x 0.37 mm)

· Included output matching circuit

Included very robust bandgap regulator (Small Vcc and TA dependence)

· Included protection circuits for ESD

APPLICATION

· Low noise amplifier for GPS

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPC8236T6N-E2	µРС8236Т6N-E2-A	6-pin plastic TSON (Pb-Free)	6S	8 mm wide embossed tapingPin 1, 6 face the perforation side of the tapeQty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.

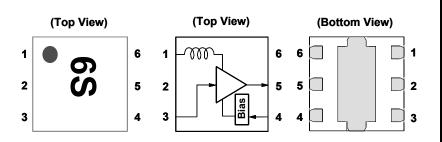
Part number for sample order: µPC8236T6N-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

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PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name	
1	Vcc	
2	GND	
3	INPUT	
4	Power Save	
5	OUTPUT	
6	Vcc	

Remark Exposed pad : GND

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Test Conditions	Ratings	Unit
Supply Voltage	Vcc	TA = +25°C	4.0	V
Power-Saving Voltage	V _{PS}	TA = +25°C	4.0	V
Total Power Dissipation	Ptot		150	mW
Operating Ambient Temperature	TA		-40 to +85	°C
Storage Temperature	Tstg		–55 to +150	°C
Input Power	Pin		+10	dBm

RECOMMENDED OPERATING RANGE

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc	1.6	2.7	3.3	V
Operating Ambient Temperature	TA	-40	+25	+85	°C
Power Save Turn-on Voltage	V _{PSon}	1.0	-	Vcc	V
Power Save Turn-off Voltage	VPSoff	0	_	0.4	V

ELECTRICAL CHARACTERISTICS

(TA = +25°C, Vcc = Vps = 2.7 V, fin = 1 575 MHz, unless otherwise specified)

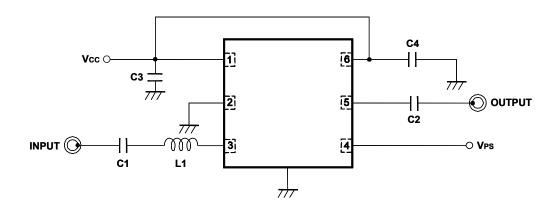
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Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit	
Circuit Current	Icc	No Signal (V _{PS} = 2.7 V)	5.0	6.5	8.0	mA	
		At Power-Saving Mode (V _{PS} = 0 V)	-	-	1	μA	
Power Gain	G₽	Pin = -35 dBm	17	19.5	22	dB	
Noise Figure	NF		-	0.8	1.1	dB	
Input Return Loss	RLin		7.5	11	-	dB	
Output Return Loss	RLout		11	14	-	dB	

STANDARD CHARACTERISTICS FOR REFERENCE

(TA = +25°C, Vcc = Vps = 2.7 V, fin = 1 575 MHz, unless otherwise specified)

Parameter	Symbol	Test Conditions	Reference	Unit
Isolation	ISL		39	dB
Input 3rd Order Distortion Intercept Point	IIP3	fin1 = 1 575 MHz, fin2 = 1 574 MHz	-3	dBm
Gain 1 dB Compression Input Power	Pin (1 dB)		-18	dBm

TEST CIRCUIT

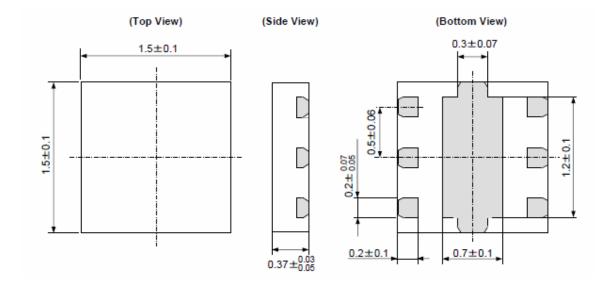


COMPONENTS LIST

Symbol	Туре	Value	Unit
C1	Chip Capacitor	1000	pF
C2	Chip Capacitor	1.0	pF
C3	Chip Capacitor	1000	pF
C4	Chip Capacitor	1000	pF
L1	Chip Inductor	4.7	nH

PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)



NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation).
 All the ground terminals must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.
- (4) Do not supply DC voltage to INPUT pin.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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